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(54) **DIRECT PLATING OF COPPER ON  
DIELECTRICS FOR GLASS CORE PLATING**

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**ABSTRACT**

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In an embodiment, a package substrate is described. In an embodiment, the package substrate comprises a layer, where the layer is a dielectric material. In an embodiment, a via opening is provided through a thickness of the layer. In an embodiment, a conductive via is in the via opening, where the conductive via has a substantially uniform composition throughout a thickness of the conductive via. In an embodiment the conductive via directly contacts the layer.

